DEVICE FOR TRANSFERRING A SEMICONDUCTOR WAFER

Abstract of the Disclosure

A device for use in handling a semiconductor wafer from a front face of the wafer on which a finished surface is formed by processing of the semiconductor wafer, the front face including an outer peripheral edge margin. The device includes fingers having tip portions adapted to engage the wafer for use in holding the wafer and a frame mounting the fingers and positively locating the fingers for simultaneously engaging the wafer only on the outer peripheral edge margin of the wafer. The device further includes vacuum pressure passages terminating at the tip portions of the fingers for applying a vacuum pressure through the finger tip portions to the wafer to grip the wafer. The fingers are arranged for holding the wafer in a single predetermined orientation.

Fig. 1